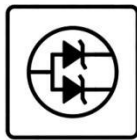


# MSKSEMI

SEMICONDUCTOR



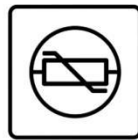
ESD



TVS



TSS



MOV



GDT

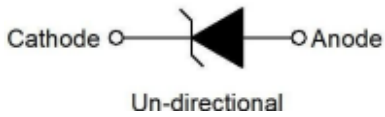


PLED

Product data sheet



SOD-123FL



### Features

- Glass passivated or planar junction
- Excellent clamping capability
- Repetition rate (duty cycle): 0.01%
- Low profile package and low inductance
- Fast response time: typically less than 1.0ps from 0V to  $V_{BRmin}$ .
- High temperature soldering: 260°C/10s atterminals.
- For surface mounted applications in ordertooptimize board space.

### Mechanical Characteristics

Package: SOD-123FL

- Case Material: “Green” MoldingCompound.
- UL Flammability Classification Rating 94V-0
- Polarity: Color band denotes cathode except bi-directional models
- Weight: 0.017g
- Terminal Connections: See Diagram Below
- Marking Information: See Below

### Applications

- I/O Interface.
- Power lines
- Automotive and Telecommunication

Industrial Electronics

### Electrical Characteristics (T=25°C)

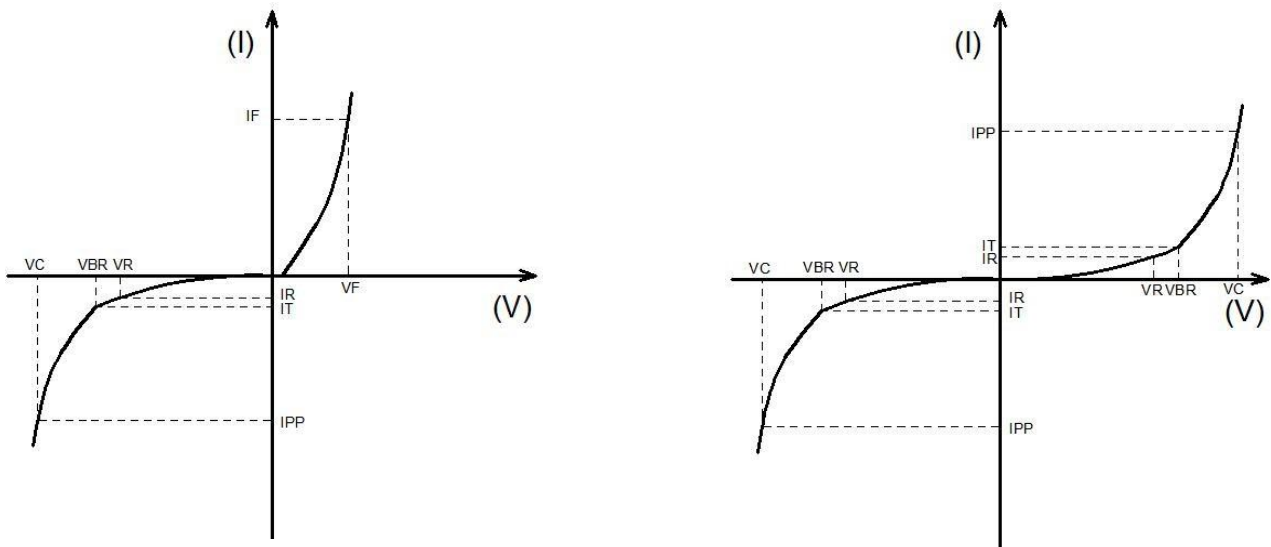
P/N	MARK	$V_R$	$I_R@V_R$	$V_{BR}@I_T$		$I_T$	$V_C@I_{PP}$	$I_{PP}^{\text{①}}$
		V	$\mu A$	min(V)	max(V)	mA	max(V)	A
SMF3.3A	3.3A	3.3	200	5.2	6	10	8.0	25.00

Absolute Maximum Ratings(T=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 10/1000µs waveform	$P_{PP}$	200	W
Steady state power dissipation at $T_L=75^\circ\text{C}$	$P_{M(AV)}$	1.0	W
Operating junction temperature range	$T_j$	-55 to +125	$^\circ\text{C}$
Storage temperature range	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Ratings And V-I Characteristics Curves (T=25°C, unless otherwise noted)

FIG1: V-I cure characteristics



Symbol	Parameter
$I_F$	Mean Forward Current
$V_F$	Maximum Forward Voltage @ $I_F$
$V_R$	Peak Reverse Working Voltage
$I_R$	Reverse Leakage Current @ $V_R$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$

Typical Characteristics

FIG2: Pulse Derating Curve

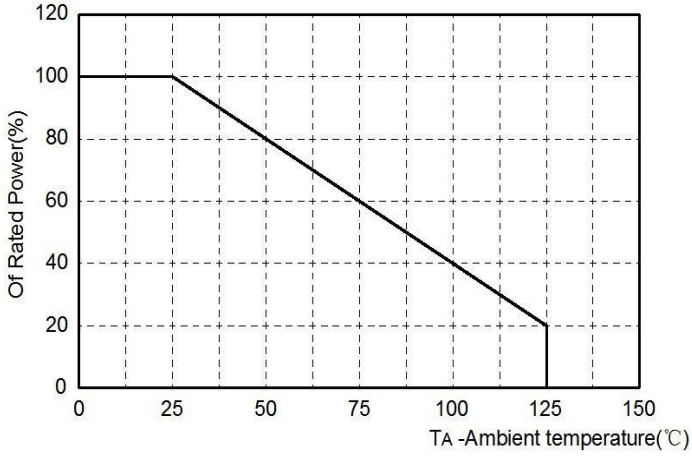


FIG3: Pulse Waveform

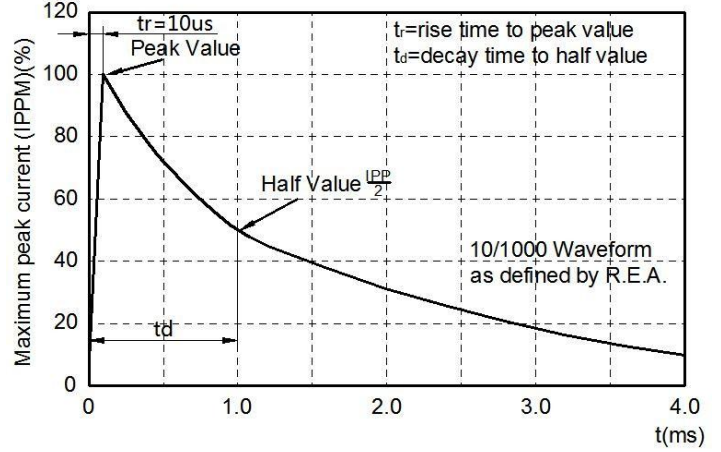


FIG4: Peak Pulse Power Rating Curve

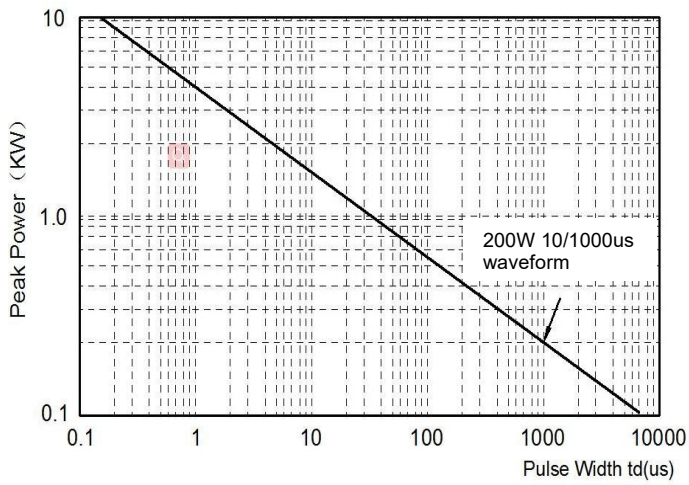
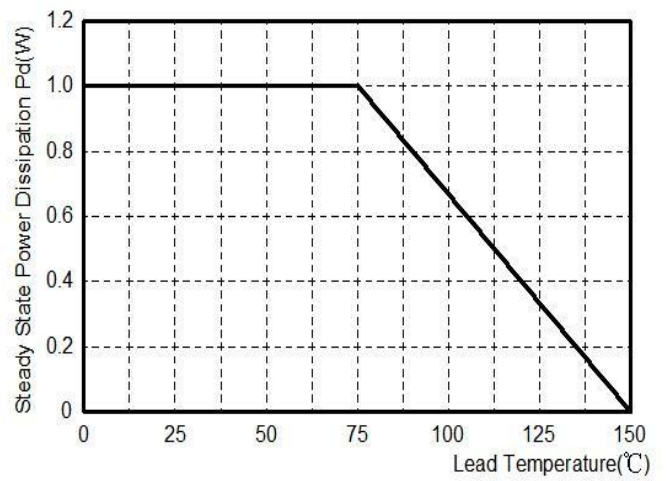
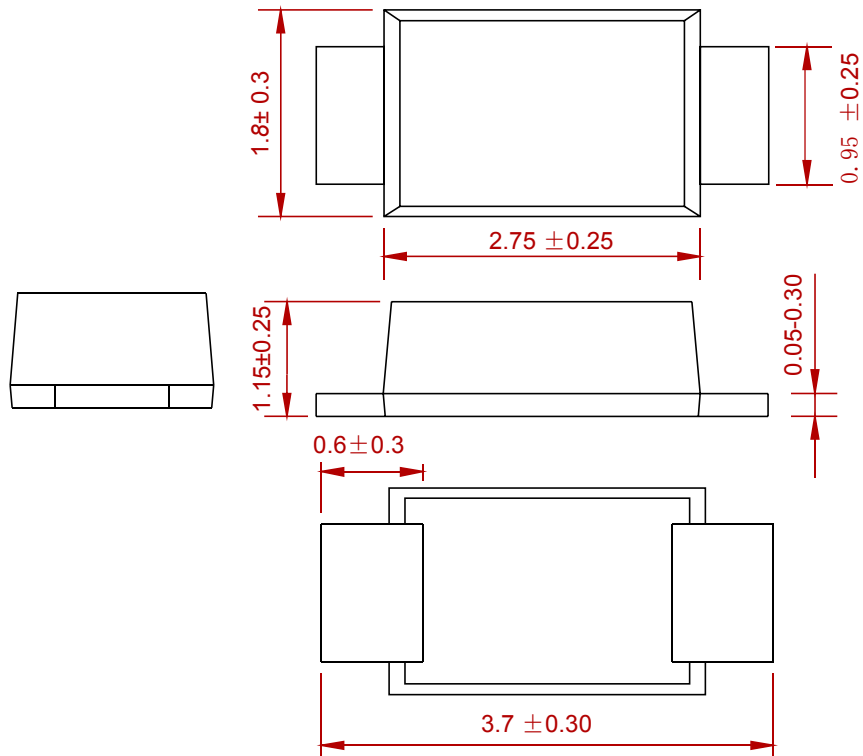


FIG5: Steady State Power Dissipation

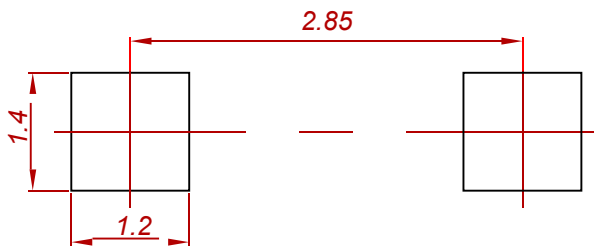


**PACKAGE MECHANICAL DATA**



*Dimensions in millimeters*

**Suggested Pad Layout**



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.05$  mm.
3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
SMF3.3A	SOD-123FL	3000

## Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.